



## General Description

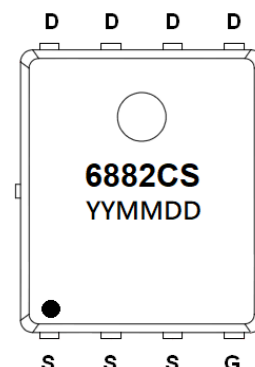
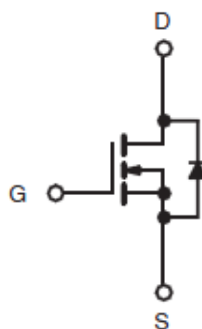
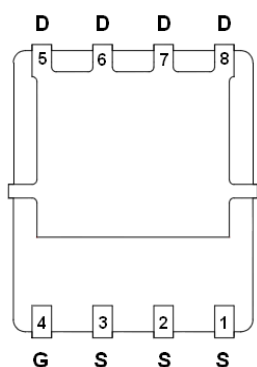
AFN6882CS, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- 100V/20A,  $R_{DS(ON)} = 7.8m\Omega @ V_{GS} = 10V$
- 100V/15A,  $R_{DS(ON)} = 10.6m\Omega @ V_{GS} = 4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- DFN5X6-8L package design

## Pin Description ( DFN5X6-8L )



## Application

- Networking / Telecom / Server
- LED Lighting Applications
- Quick Charger Applications
- DC-DC Primary Side Switch

## Pin Define

Pin	Symbol	Description
1~3	S	Source
4	G	Gate
5~8	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN6882CSFN568RG	6882CS	DFN5X6-8L	Tape & Reel	2500 EA

※ 6882CS : Parts Code

※ YYMMDD : Date Code

※ AFN6882CSFN568RG : 13" Tape & Reel ; Pb- Free ; Halogen- Free



### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ Unless otherwise noted)

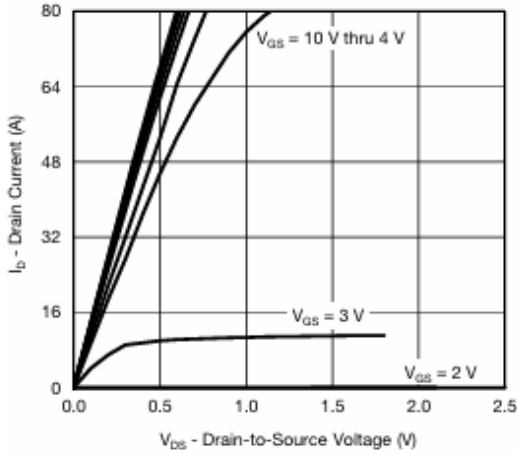
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate -Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_J=150^\circ\text{C}$ )	$I_{DSM}$	$T_C=25^\circ\text{C}$	60
		$T_C=70^\circ\text{C}$	55
Pulsed Drain Current ( $t=100\mu\text{s}$ )	$I_{DM}$	$T_A=25^\circ\text{C}$	17
		$T_A=70^\circ\text{C}$	14
Continuous Source Current (Diode Conduction)	$I_S$	$T_C=25^\circ\text{C}$	60
		$T_A=25^\circ\text{C}$	4.9
Single Pulse Avalanche Current	$I_{AS}$	30	mJ
	$E_{AS}$	45	
Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	83
		$T_C=75^\circ\text{C}$	53
Operating Junction Temperature	$T_J$	$T_A=25^\circ\text{C}$	5.4
		$T_A=75^\circ\text{C}$	3.4
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	18	$^\circ\text{C/W}$
Maximum Junction-to-Case (Drain)	$R_{\theta JA}$	1.0	

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ Unless otherwise noted)

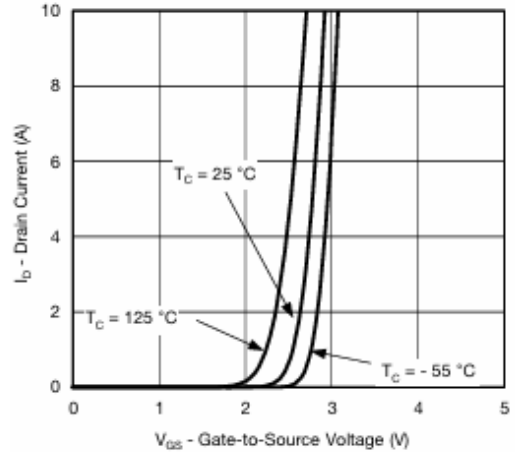
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.7	2.5	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$			1	uA
		$V_{DS}=80V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5V, V_{GS}=10V$	30			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		7.0	7.8	m $\Omega$
		$V_{GS}=4.5V, I_D=15A$		9.2	10.6	
Forward Transconductance	$g_{FS}$	$V_{DS}=10V, I_D=20A$		60		S
Diode Forward Voltage	$V_{SD}$	$I_S=5A, V_{GS}=0V$		0.75	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=50V, V_{GS}=4.5V$ $I_D=20A$		19.5	35	nC
Gate-Source Charge	$Q_{gs}$			5.8		
Gate-Drain Charge	$Q_{gd}$			8.5		
Gate Resistance	$R_g$	$f=1\text{MHz}$	0.4	1.2	2.0	$\Omega$
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V$ $f=1\text{MHz}$		1950		pF
Output Capacitance	$C_{oss}$			750		
Reverse Transfer Capacitance	$C_{rss}$			60		
Turn-On Time	$t_{d(on)}$	$V_{DD}=50V, R_L=5\Omega$ $I_D=10A, V_{GEN}=10V$ $R_G=1\Omega$		10	20	ns
	$t_r$			15	30	
Turn-Off Time	$t_{d(off)}$			35	70	
	$t_f$			10	20	



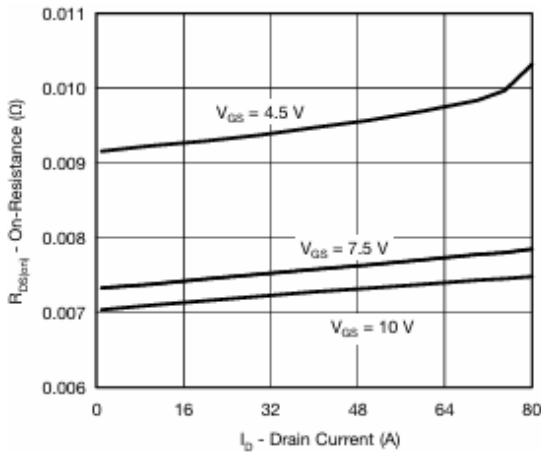
**Typical Characteristics**



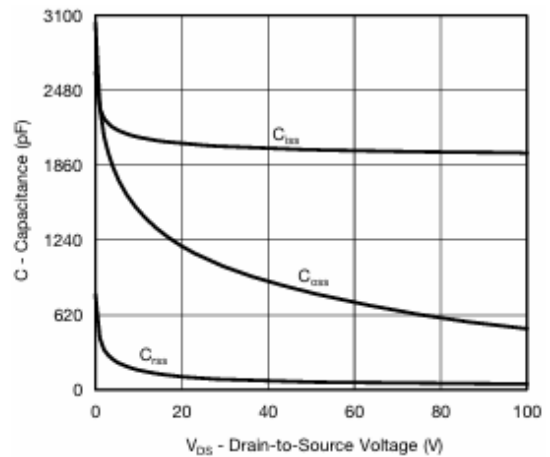
**Output Characteristics**



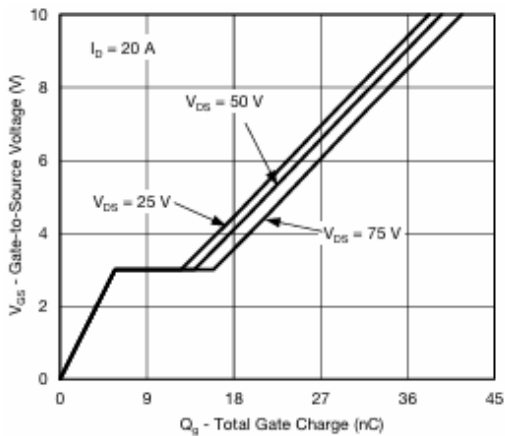
**Transfer Characteristics**



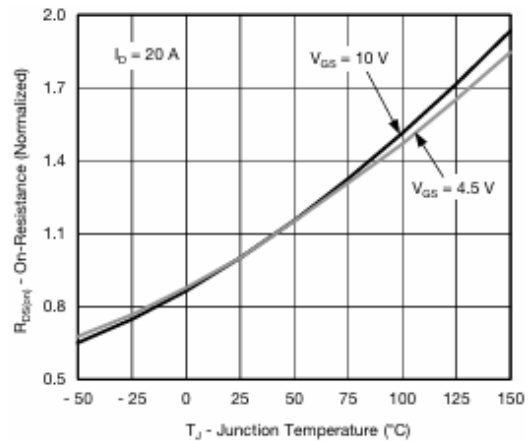
**On-Resistance vs. Drain Current and Gate Voltage**



**Capacitance**



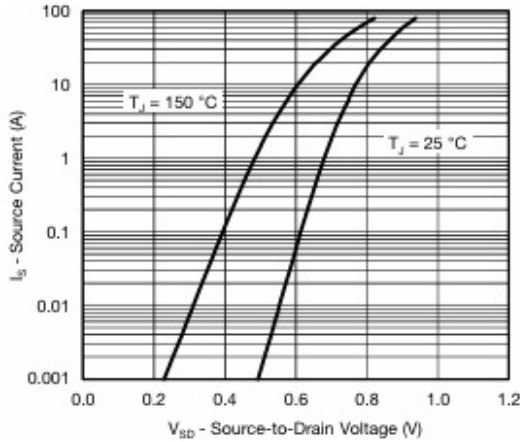
**Gate Charge**



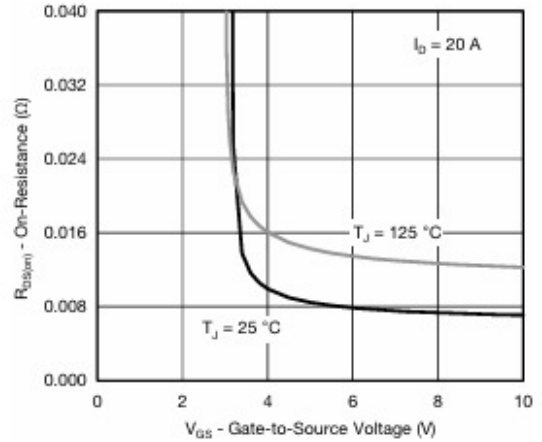
**On-Resistance vs. Junction Temperature**



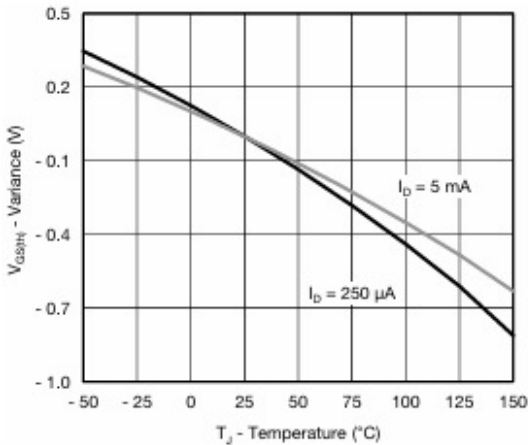
**Typical Characteristics**



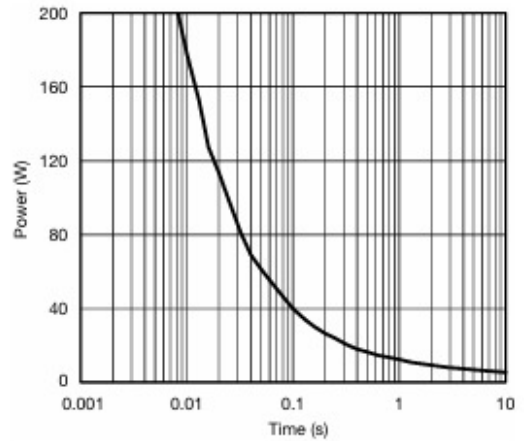
**Source-Drain Diode Forward Voltage**



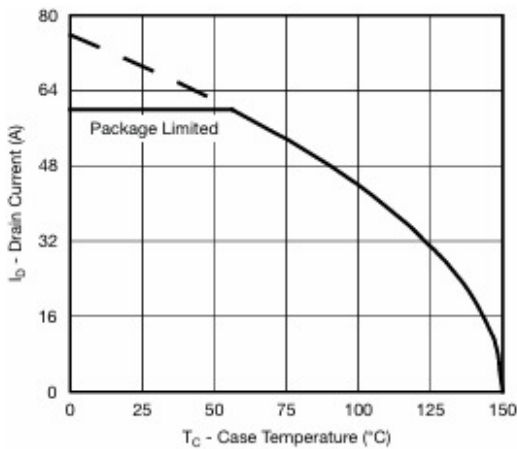
**On-Resistance vs. Gate-to-Source Voltage**



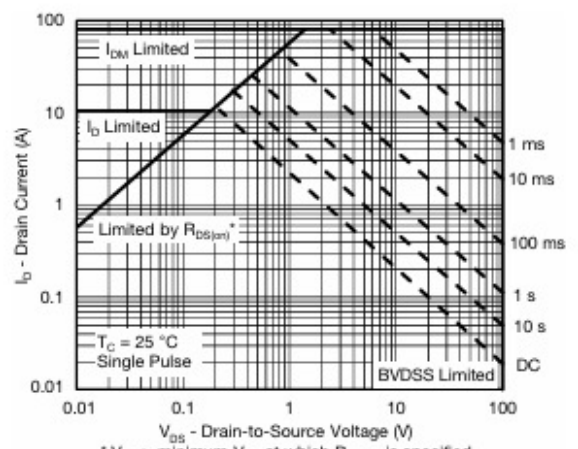
**Threshold Voltage**



**Single Pulse Power, Junction-to-Ambient**



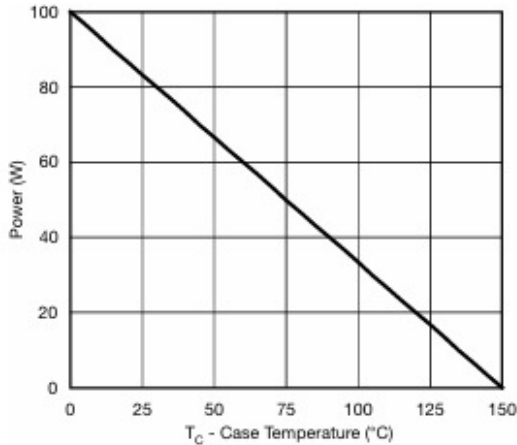
**Current Derating\***



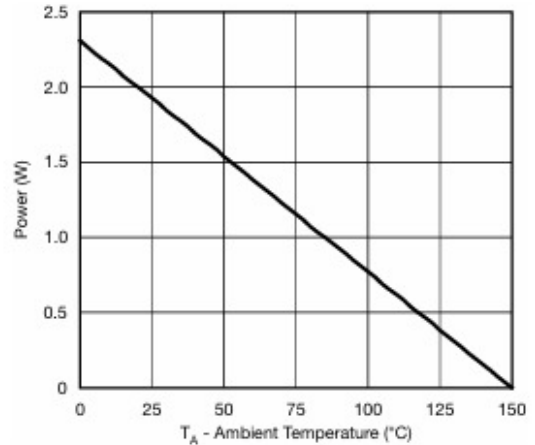
**Safe Operating Area, Junction-to-Ambient**



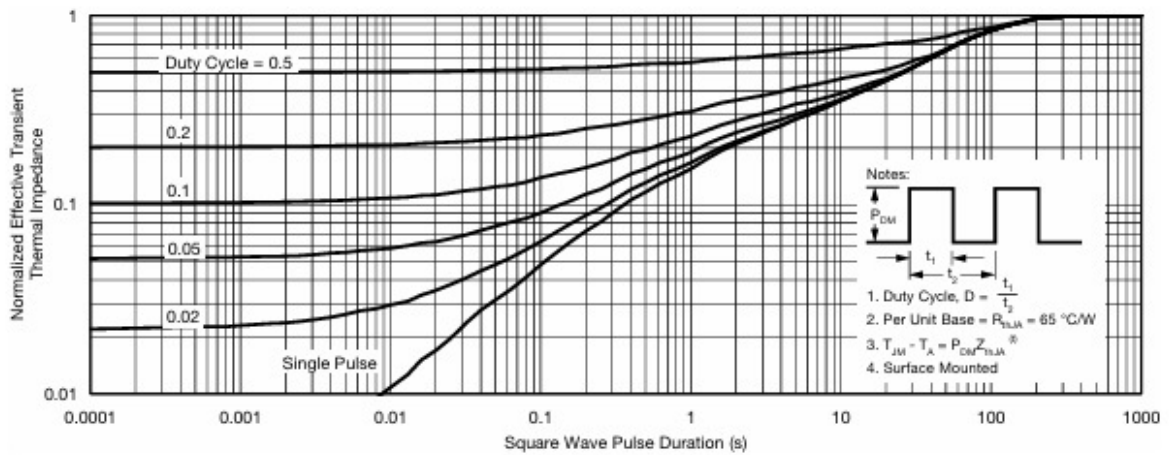
## Typical Characteristics



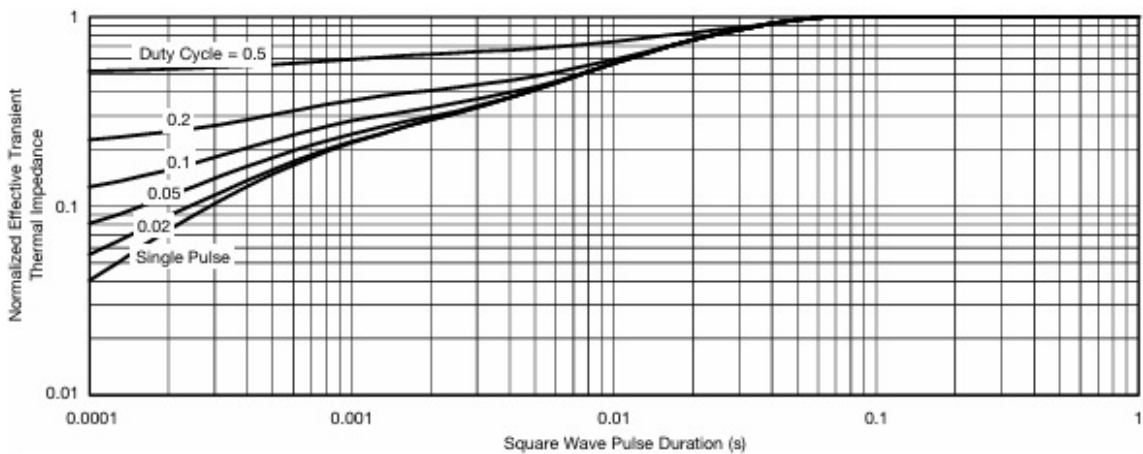
Power, Junction-to-Case



Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

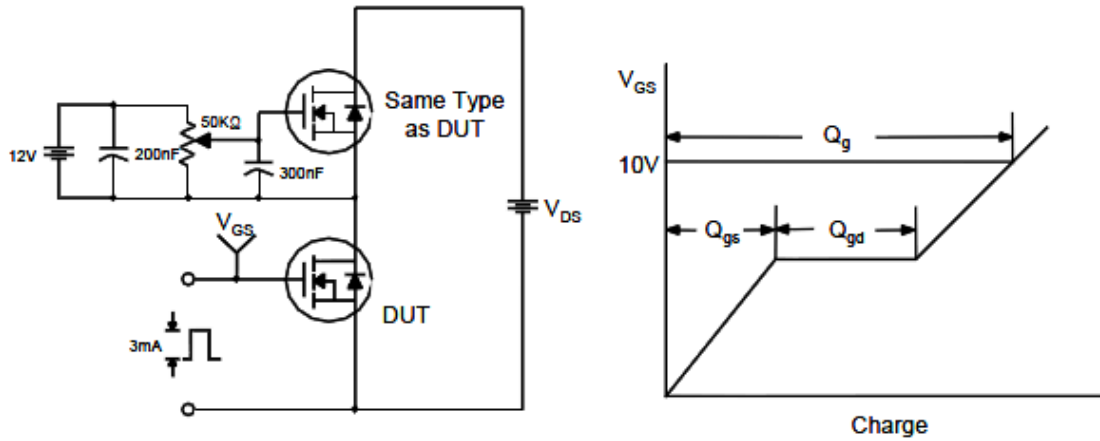


Normalized Thermal Transient Impedance, Junction-to-Case

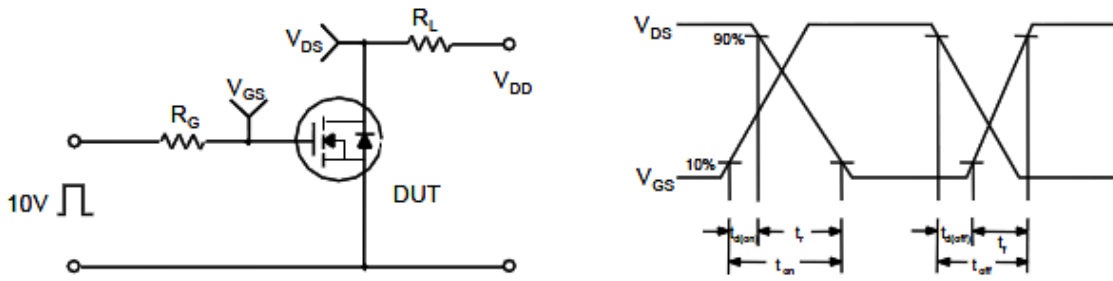


**Typical Characteristics**

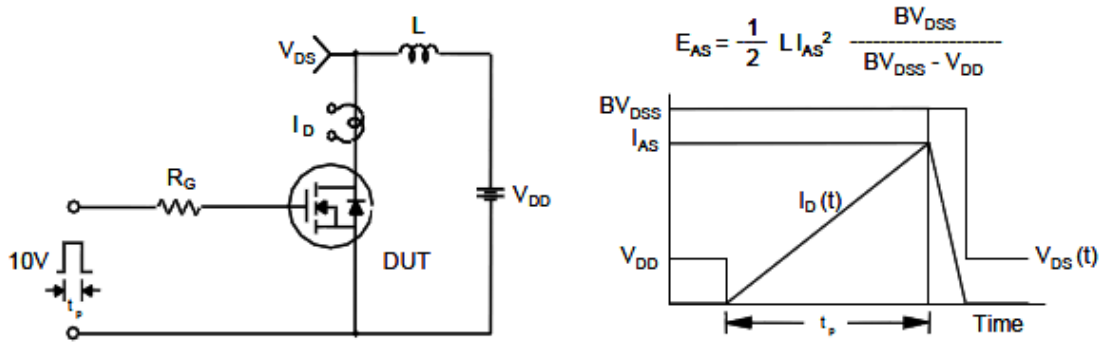
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

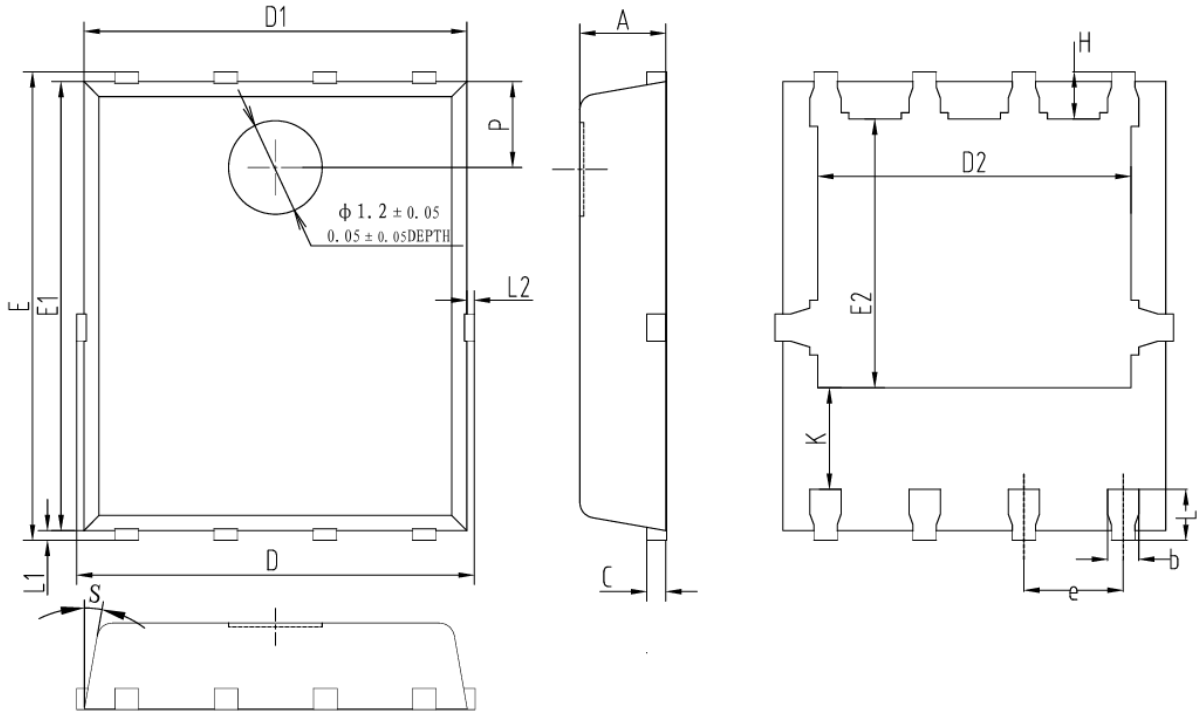


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( DFN5X6-8L )**



COMMON DIMENSIONS (UNIT of MEASURE=MILLIMETER)											
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	1.00	1.10	1.20	e	1.17	1.27	1.37	L	0.55	0.65	0.75
b	0.35	0.40	0.45	E	5.90	6.00	6.10	L1	0	0.10	0.20
c	0.19	0.25	0.30	E1	5.70	5.75	5.80	L2	0	0.10	0.20
D	4.80	5.10	5.20	E2	3.35	3.45	3.55	P	1.00	1.10	1.20
D1	4.80	4.90	5.00	H	0.50	0.60	0.70	S	8°	10°	12°
D2	3.90	4.00	4.10	K	1.20	1.30	1.40				

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